



SSC8LA14GTL

N-Channel Enhancement Mode MOSFET

Features

V _{DS}	V _{GS}	R _{DS(ON)} Typ.	I _D
100V	±20V	1.2mΩ@10V	403A

Description

The SSC8LA14GTL is N-Channel enhancement mode MOSFET. Uses SGT Technology and design to provide excellent RDSON with low gate charge. This device is suitable for use in DC - DC conversion, power switch and charging circuit.

100% UIS + ΔVDS + Rg Tested!

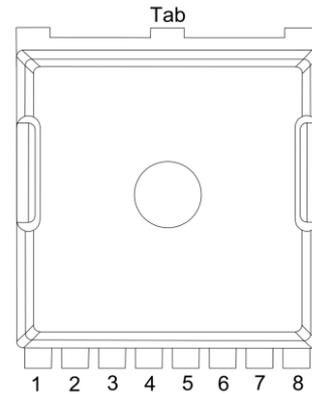
Applications

- Inverter
- DC-DC Converter
- Half and Full Bridge Topology
- Motor Drive Control

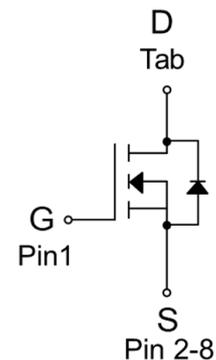
Ordering Information

Device	Package	Shipping
SSC8LA14GTL	TOLL	2000/Reel

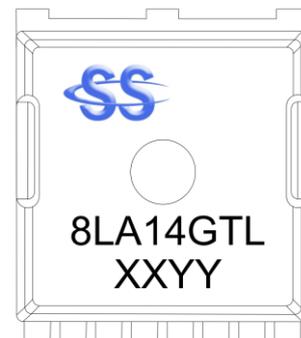
Pin configuration



TOLL (Top View)



Pin Configuration



Marking

(XXYY: Internal Traceability Code)



➤ **Absolute Maximum Ratings (T_A=25°C unless otherwise noted)**

Symbol	Parameter	Ratings	Unit	
V _{DSS}	Drain-to-Source Voltage	100	V	
V _{GSS}	Gate-to-Source Voltage	±20	V	
I _D	Continuous Drain Current ^b	T _C = 25°C	403	A
		T _C = 100°C	224	A
I _{DM}	Pulsed Drain Current ^b	1613	A	
I _{DSM}	Continuous Drain Current ^a	T _A = 25°C	36	A
		T _A = 70°C	26	A
P _D	Power Dissipation ^c	T _C = 25°C	313	W
		T _C = 100°C	125	W
P _{DSM}	Power Dissipation ^a	T _A = 25°C	2.5	W
		T _A = 70°C	1.6	W
I _{AS}	Avalanche Current ^b L = 0.5mH	72	A	
E _{AS}	Avalanche Energy ^b L = 0.5mH	1296	mJ	
T _J	Operation junction temperature	-55 to 150	°C	
T _{STG}	Storage temperature range	-55 to 150	°C	

➤ **Thermal Resistance Ratings (T_A=25°C unless otherwise noted)**

Symbol	Parameter	Ratings	Unit
R _{θJA}	Junction-to-Ambient Thermal Resistance ^a	50	°C/W
R _{θJC}	Junction-to-Case Thermal Resistance	0.4	

Note:

- a. The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with T_A=25°C. The value in any given application depends on the user's specific board design. The current rating is based on the t_{≤10s} thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P_D is based on T_{J(MAX)}=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- d. The maximum current rating is package limited.

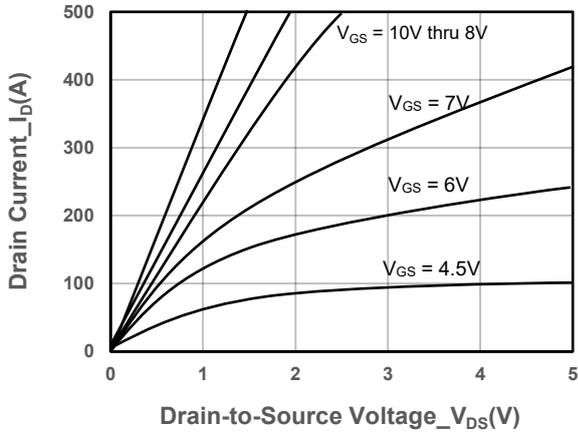


➤ **Electrical Characteristics (T_A=25°C unless otherwise noted)**

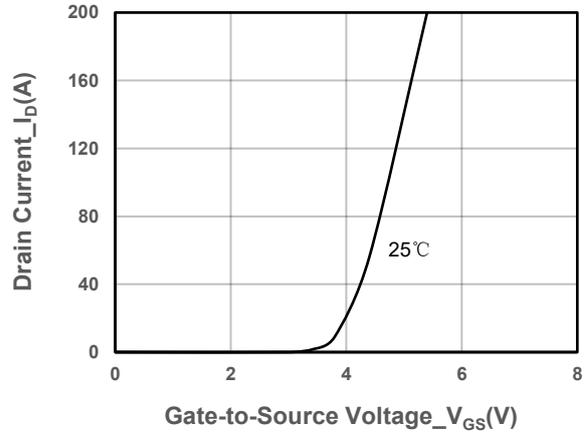
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	100			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250uA	2.0	3.0	4.0	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 20A		1.2	1.9	mΩ
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 100V, V _{GS} = 0V			1	μA
Gate-Source Leak Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±150	nA
Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = 20A		0.75	1.3	V
Gate Resistance	R _G	V _{DS} = 0V, f = 1MHz		2.1		Ω
Input Capacitance	C _{ISS}	V _{DS} = 50V, V _{GS} = 0V, f = 1MHz		15000		pF
Output Capacitance	C _{OSS}			2500		
Reverse Transfer Capacitance	C _{RSS}			220		
Total Gate Charge	Q _G	V _{GS} = 10V, V _{DS} = 50V, I _D = 20A		205		nC
Gate to Source Charge	Q _{GS}			60		
Gate to Drain Charge	Q _{GD}			50		
Turn-on Delay Time	T _{D(ON)}	V _{GS} = 10V, V _{DS} = 50V, I _D = 20A, R _G = 3.3Ω		40		ns
Rise Time	T _r			95		
Turn-off Delay Time	T _{D(OFF)}			110		
Fall Time	T _f			135		
Diode Recovery Time	T _{rr}	I _F =20A, di/dt=100A/us		100		ns
Diode Recovery Charge	Q _{rr}	I _F =20A, di/dt=100A/us		210		nC



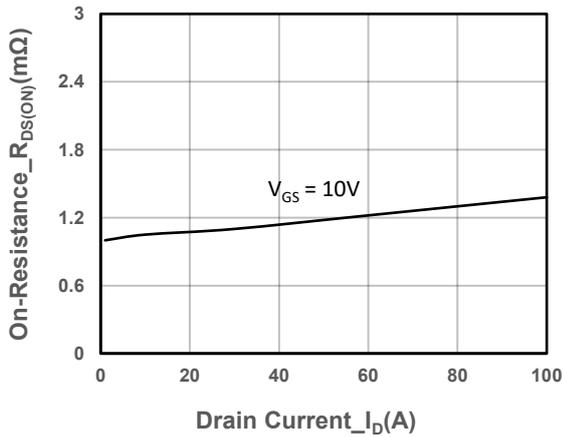
Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)



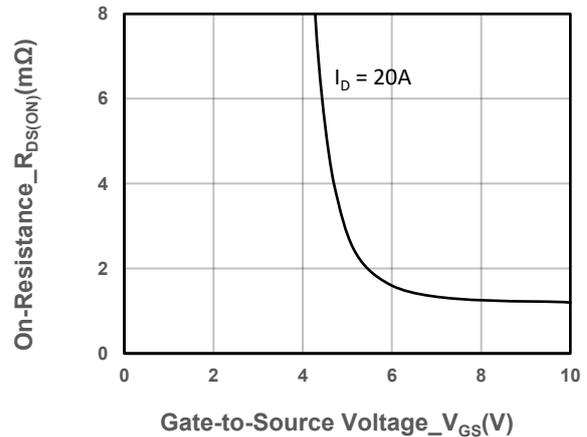
Output Characteristics



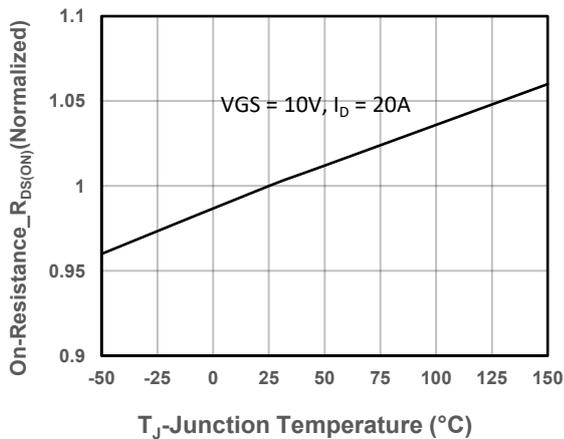
Transfer Characteristics



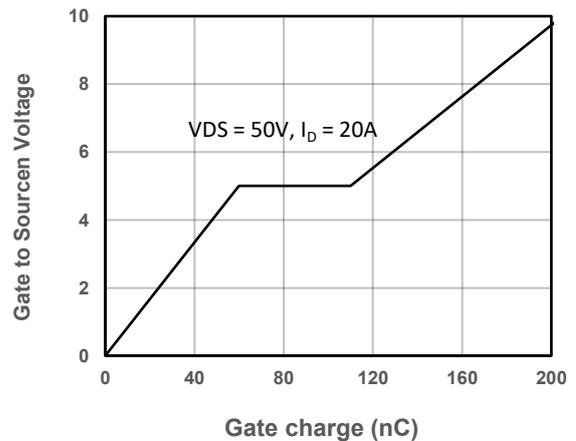
On-Resistance vs. Drain Current and Gate Voltage



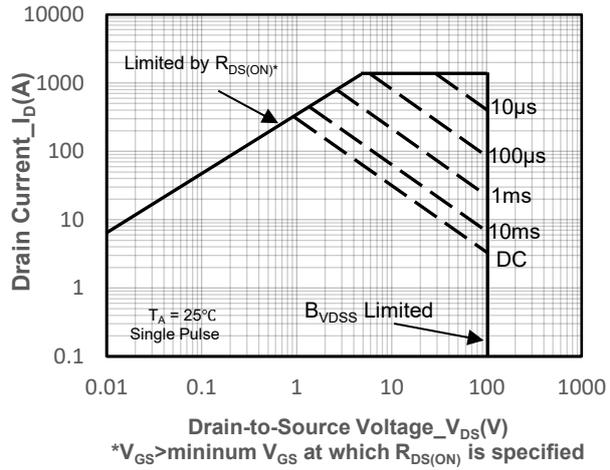
On-Resistance vs. Gate-to-Source Voltage



On-Resistance vs. Junction Temperature

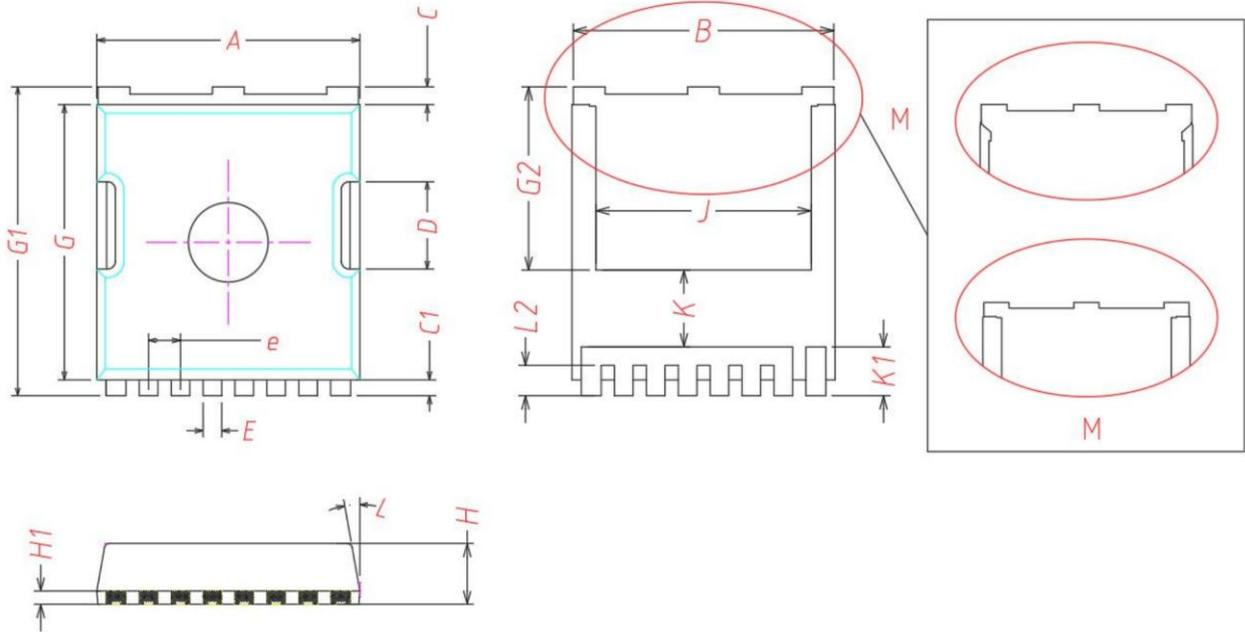


Gate-Source Voltage vs. Gate charge



Safe Operating Area vs. Junction-to-Ambient

Package Information



Symbol	MILL IMETER			Symbol	MILL IMETER		
	Min	Nom	Max		Min	Nom	Max
A	9.70	9.90	10.10	G2	6.80	7.00	7.15
B	9.60	9.80	10.00	H	2.20	2.30	2.40
C	0.55	0.65	0.85	H1	0.40	0.50	0.60
C1	0.45	0.60	0.75	J	8.00	8.50	9.25
D	2.85	3.30	3.45	K	2.80	3.00	3.20
E	0.60	0.85	0.90	L	8°	10°	12°
e	1.2 BSC			K1	1.55	1.80	1.86
G	10.15	10.40	10.60	L2	1.00	1.15	1.30
G1	11.50	11.70	11.85				



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